

AMENDMENT UNDER 37 C.F.R. § 1.111
Application Number: 10/516,708
Attorney Docket Number: Q85154

AMENDMENTS TO THE SPECIFICATION

Please replace the description on page 18, lines 6-15, with the following amended description:

As illustrated in FIG. 7, if the solder-(~~▲, ×, ●~~) in accordance with Example 3 contains Bi at 6 weight % or smaller-(~~▲, ×~~), the solder provides a shearing strength equal to or higher than the same of Sn-37 wt.% Pb eutectic solder-(~~⊖~~) even after 1000 cycles in the thermal cycle test.

However, if the solder contains Bi at 30 weight % or higher-(~~●~~), a shearing strength thereof is lower than that of Sn-37 wt.% Pb eutectic solder except immediately after an electronic component has been mounted on a circuit substrate. In addition, after 1000 cycles, a shearing strength of the solder containing Bi at 6 weight % or higher is lower than that of the conventional Sn-37 wt.% Pb eutectic solder.

Please replace the description on page 24, lines 3-9, with the following amended description:

As illustrated in FIG. 11 A, when a circuit substrate including non-coated copper electrodes, the solder-(~~●~~) containing Ag at 0.1 weight % explicitly has a higher shearing strength than a solder-(~~▲~~) not containing Ag before or after a thermal cycle was applied to the solder.

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As illustrated in FIG. 11 B, when a circuit substrate including copper electrodes coated with a Ni layer and an Au layer by plating or evaporation, the solder-(●) containing Ag at 0.1 weight % explicitly has a higher shearing strength than a solder-(▲) not containing Ag before or after a thermal cycle was applied to the solder.